TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK3067

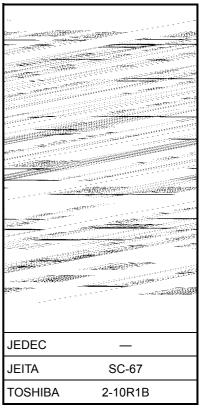
# Chopper Regulator, DC-DC Converter and Motor Drive Applications

Unit: mm

| • | Low drain-source ON res   | istance          | $: R_{DS}(ON) = 4.2 \Omega \text{ (typ.)}$                           |
|---|---------------------------|------------------|--|
| • | High forward transfer adı | mittance         | $ Y_{fs}  = 1.7 \text{ S (typ.)}$                                    |
| • | Low leakage current       | $: I_{DSS} = 1$  | $100 \mu\text{A} (\text{max}) (\text{V}_{\text{DS}} = 600 \text{V})$ |
| • | Enhancement-mode          | $: V_{th} = 2.0$ | $0\sim4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$   |
|   |                           |                  |  |

#### **Maximum Ratings (Tc = 25°C)**

| Characteristics     |                                | Symbol           | Rating                              | Unit  |     |    |
|---------------------|--------------------------------|------------------|-------------------------------------|---|-----|----|
| Drain-source volta  | ge                             | $V_{DSS}$        | 600                                 | V   |     |    |
| Drain-gate voltage  | (R <sub>GS</sub> = 20 kΩ)      | $V_{DGR}$        | 600                                 | V   |     |    |
| Gate-source voltage | ge                             | $V_{GSS}$        | ±30                                 | V   |     |    |
|                     | DC (Note 1)                    | I <sub>D</sub>   | 2                                   | Α   |     |    |
| Drain current       | Pulse (t = 1 ms)<br>(Note 1)   | I <sub>DP</sub>  | 5                                   | Α   |     |    |
|                     | Pulse (t = 100 μs)<br>(Note 1) | I <sub>DP</sub>  | 8                                   | 000 V |     |    |
| Drain power dissip  | ation                          | P <sub>D</sub>   | 25                                  | W   |     |    |
| Single pulse avalar | nche energy<br>(Note 2)        | E <sub>AS</sub>  | 93                                  | mJ  |     |    |
| Avalanche current   |                                | I <sub>AR</sub>  | 2                                   | Α   |     |    |
| Repetitive avalance | ive avalanche energy (Note 3)  |                  | epetitive avalanche energy (Note 3) |   | 2.5 | mJ |
| Channel temperatu   | ire                            | T <sub>ch</sub>  | 150                                 | °C  |     |    |
| Storage temperatu   | re range                       | T <sub>stg</sub> | -55~150                             | °C  |     |    |



Weight: 1.9 g (typ.)

#### **Electrical Characteristics (Tc = 25°C)**

| Characteristics                     | Symbol                 | Max  | Unit   |
|-------------------------------------|------------------------|------|--------|
| Thermal reverse, channel to case    | R <sub>th (ch-c)</sub> | 5.0  | °C/W   |
| Thermal reverse, channel to ambient | R <sub>th (ch-a)</sub> | 62.5 | °C / W |

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 41 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 2 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

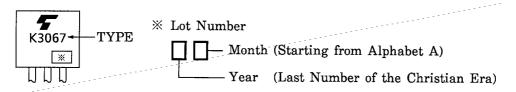
## **Electrical Characteristics (Tc = 25°C)**

| Characteristics Symbol                          |                          | Symbol  | Test Condition  | Min | Тур. | Max | Unit |
|---|--------------------------|---|---|-----|------|-----|------|
| Gate leakage current                            |                          | $I_{GSS}$   | V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V                        | _   | _    | ±10 | μΑ   |
| Gate-source breakdown voltage                   |                          | V (BR) GSS  | I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V                        | ±30 | _    | _   | V    |
| Drain cut-off current                           |                          | I <sub>DSS</sub>  | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V                        | _   | _    | 100 | μA   |
| Drain-source breakdown voltage                  |                          | V <sub>(BR)DSS</sub>  | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V                         | 600 | _    | _   | V    |
| Gate threshold voltage                          |                          | $V_{th}$  | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA                         | 2.0 | _    | 4.0 | V    |
| Drain-source ON resistance                      |                          | R <sub>DS</sub> (ON)  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A                          | _   | 4.2  | 5.0 | Ω    |
| Forward transfer admittance                     |                          | Y <sub>fs</sub>   | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 A                          | 0.8 | 1.7  | _   | S    |
| Input capacitano                                | е                        | C <sub>iss</sub>  |   | _   | 380  | _   |      |
| Reverse transfer capacitance                    |                          | C <sub>rss</sub>  | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz              | _   | 40   | _   | pF   |
| Output capacitar                                | nce                      | C <sub>oss</sub>  | ]   | _   | 120  | _   |      |
|   | Rise time                | t <sub>r</sub>  | $V_{GS}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$            | _   | 15   | _   |      |
| Switching time                                  | Turn-on time             | t <sub>on</sub>   |   | _   | 25   | -   | ns   |
| Switching time                                  | Fall time t <sub>f</sub> | \(\frac{1}{m}\) \(\frac{1}{m} | _   | 20  | ı    | 115 |      |
|   | Turn-off time            | t <sub>off</sub>  | Duty $\leq 1\%$ , $t_{\mathbf{w}} = 10 \mu s$                         | _   | 80   |     |      |
| Total gate charge (Gate-source plus gate-drain) |                          | Qg  | V <sub>DD</sub> ≈ 480 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2 A |     | 9    |     |      |
| Gate-source charge                              |                          | Q <sub>gs</sub>   |   | _   | 5    | _   | nC   |
| Gate-drain ("miller") charge                    |                          | $Q_{gd}$  |   |     | 4    | _   |      |

## **Source-Drain Ratings and Characteristics (Tc = 25°C)**

| Characteristics                           | Symbol           | Test Condition   | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _  | _   | 1    | 2    | Α    |
| Pulse drain reverse current               | I <sub>DRP</sub> | t = 1 ms   | _   | _    | 5    | Α    |
| (Note 1)                                  | I <sub>DRP</sub> | t = 100 μs   | _   | _    | 8    | Α    |
| Forward voltage (diode)                   | $V_{DSF}$        | I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V                                       | _   | -    | -1.5 | ٧    |
| Reverse recovery time t <sub>rr</sub>     | t <sub>rr</sub>  | I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V<br>dI <sub>DR</sub> / dt = 100 A / μs | _   | 1000 | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  |  | -   | 5.0  | 1    | μC   |

## Marking



2 2002-06-05

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